

ABSTRACT

A semiconductor device includes a semiconductor chip having a main surface provided with an integrated circuit including a photoelectric converter and a first wiring for electrically connecting the integrated circuit of the semiconductor chip to respective external terminals. The semiconductor device also includes a sealing resin for sealing the main surface of the semiconductor chip and the first wiring, formed so as to have an opening over the surface of the integrated circuit and a light-transmitting cap for covering the opening of the sealing resin.